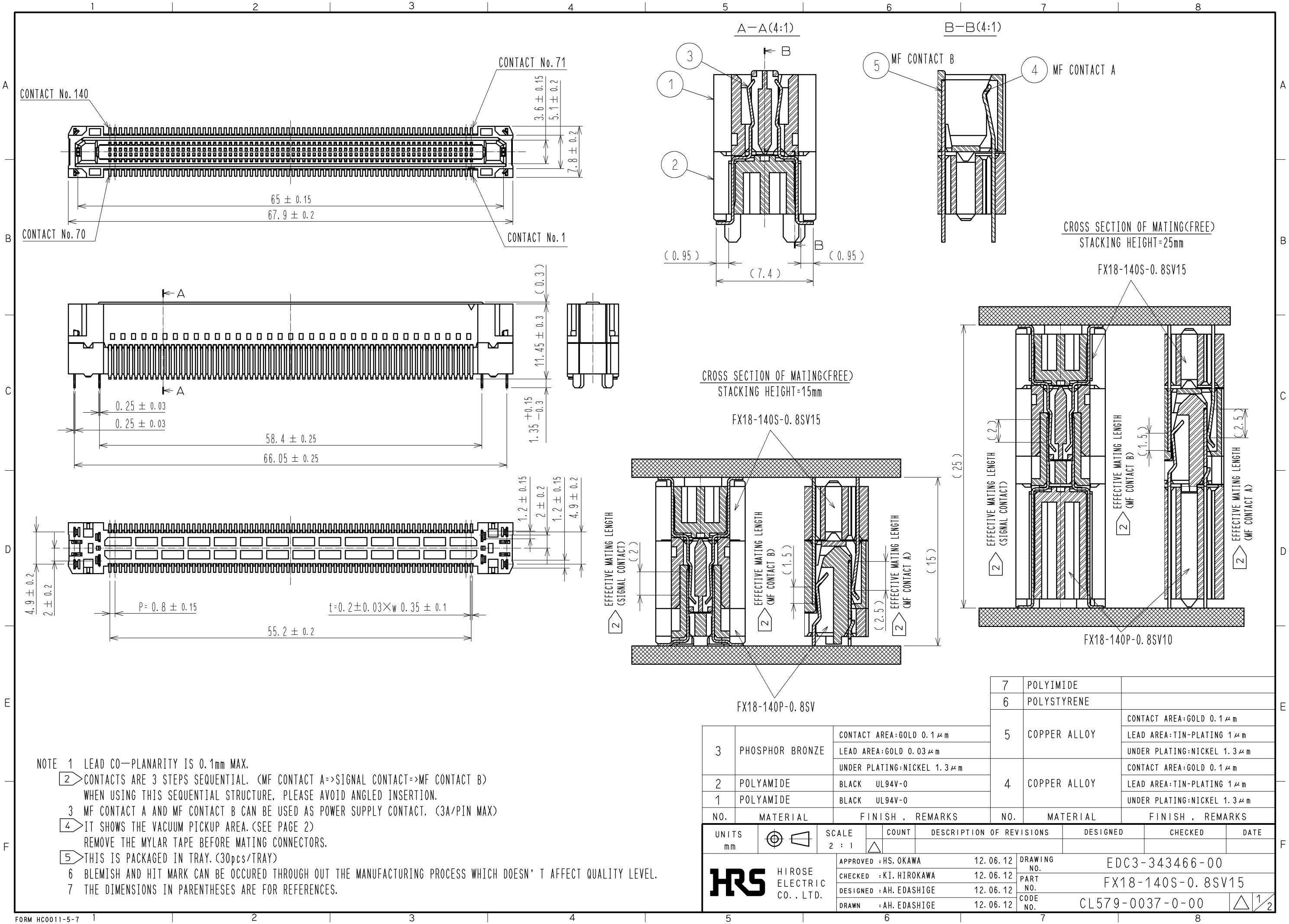


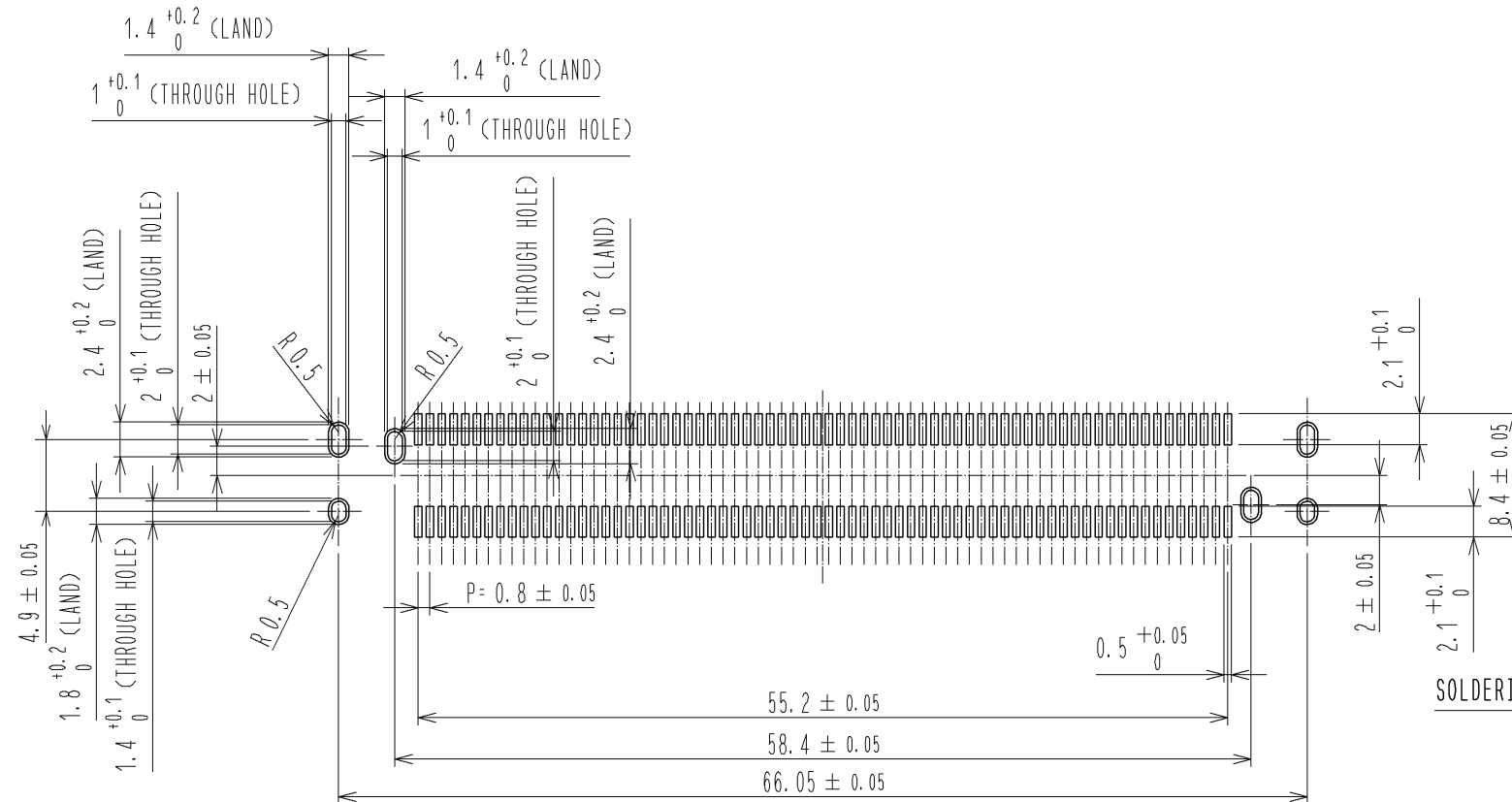
APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C <sup>(1)</sup>		STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C <sup>(2)</sup>
	VOLTAGE	100 V AC		STORAGE HUMIDITY RANGE	40 % TO 70 % <sup>(2)</sup>
	CURRENT	0.5 A (SIGNAL CONTACT) <sup>(3)</sup> 3 A (MF CONTACT)		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x x
MARKING		CONFIRMED VISUALLY.			x x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX.	x —
INSULATION RESISTANCE		250 V DC.		1000 MΩ MIN.	x —
VOLTAGE PROOF		300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x —
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 80 N MAX. WITHDRAWAL FORCE: 8 N MIN.	x —
MECHANICAL OPERATION		500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SHOCK		490 m/s <sup>2</sup> , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x —
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.	x —
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x —
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x —
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	x —
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△					
REMARKS <sup>(1)</sup> INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. <sup>(2)</sup> "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. <sup>(3)</sup> THE RATED CURRENT APPLIES TO PER CONTACT. APPLY 0.4A WHEN ALL THE CONTACTS ARE USED FOR CURRENT CARRYING. Unless otherwise specified, refer to JIS-C-5402.			APPROVED	HS. OKAWA	12. 04. 10
			CHECKED	KI. HIROKAWA	12. 04. 09
			DESIGNED	AH. EDASHIGE	12. 04. 09
			DRAWN	AH. EDASHIGE	12. 04. 09
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-343466-00
HRS		SPECIFICATION SHEET		PART NO. FX18-140S-0.8SV15	
		HIROSE ELECTRIC CO., LTD.		CODE NO. CL579-0037-0-00	△ 1/1



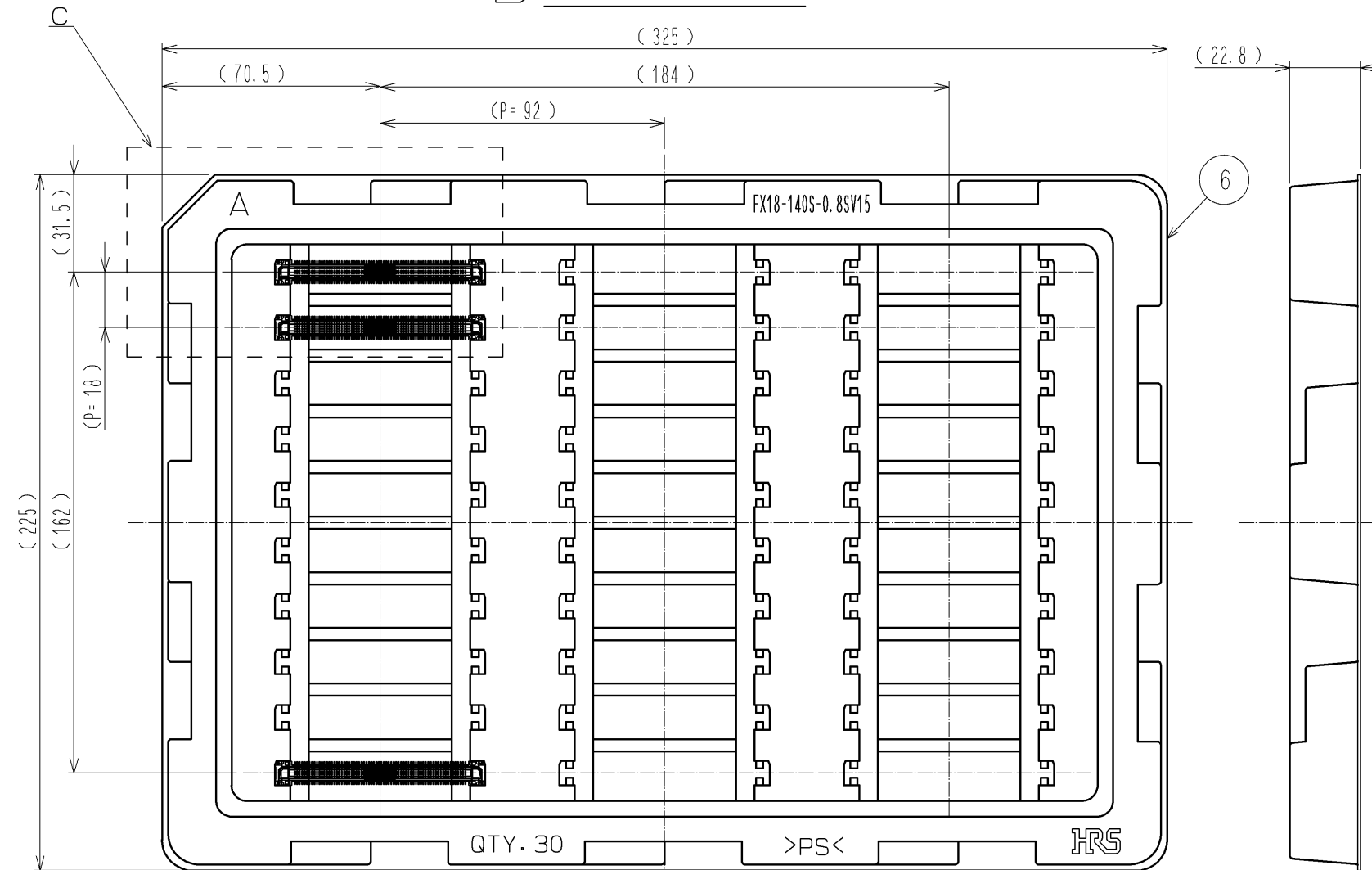
- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- 2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)  
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
- 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
- 4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)  
REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
- 5 THIS IS PACKAGED IN TRAY. (30pcs/TRAY)
- 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
- 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	7	POLYIMIDE	
		LEAD AREA:GOLD 0.03 μm	6	POLYSTYRENE	
		UNDER PLATING:NICKEL 1.3 μm	5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
2	POLYAMIDE	BLACK UL94V-0	4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
1	POLYAMIDE	BLACK UL94V-0			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm			SCALE 2 : 1		
COUNT △			DESCRIPTION OF REVISIONS		
DESIGNED HS. OKAWA			DESIGNED HS. OKAWA		
CHECKED KI. HIROKAWA			CHECKED KI. HIROKAWA		
DESIGNED AH. EDASHIGE			DESIGNED AH. EDASHIGE		
DRAWN AH. EDASHIGE			DRAWN AH. EDASHIGE		
APPROVED : HS. OKAWA			APPROVED : HS. OKAWA		
12.06.12			12.06.12		
12.06.12			12.06.12		
12.06.12			12.06.12		
12.06.12			12.06.12		
DRAWING NO. EDC3-343466-00			DRAWING NO. EDC3-343466-00		
PART NO. FX18-140S-0.8SV15			PART NO. FX18-140S-0.8SV15		
CODE NO. CL579-0037-0-00			CODE NO. CL579-0037-0-00		
1			1		

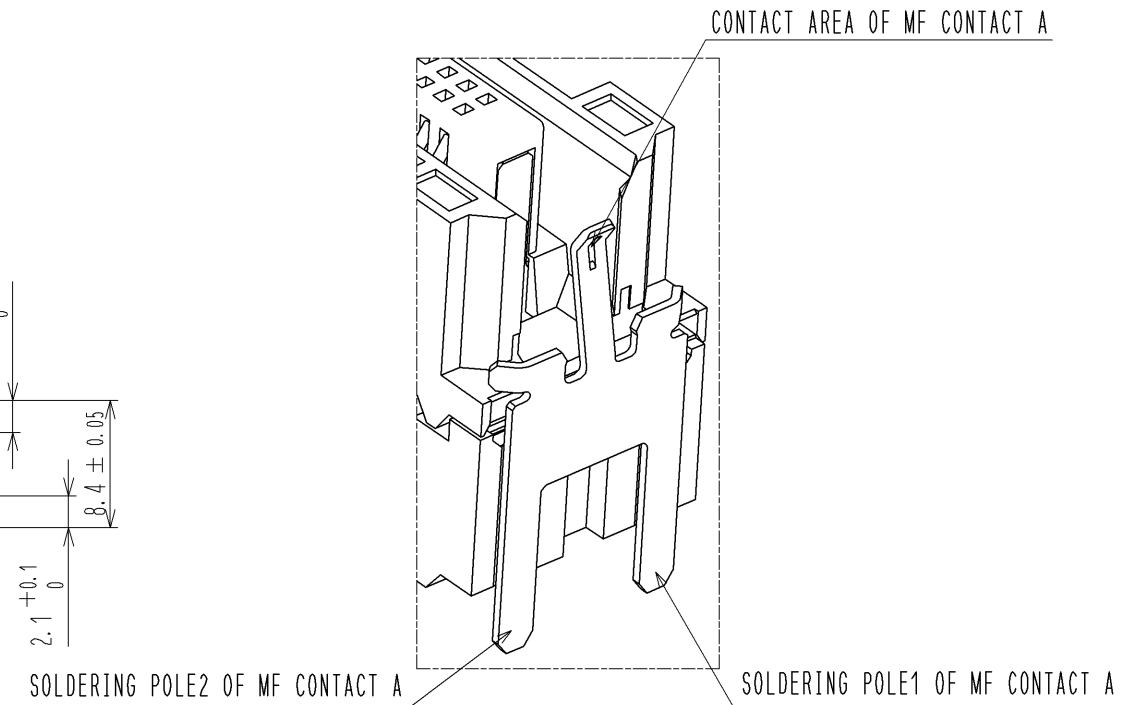
RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)  
(PCB THICKNESS:  $t=1.6\text{mm}$  METAL MASK THICKNESS:  $t=0.12\text{mm}$ )



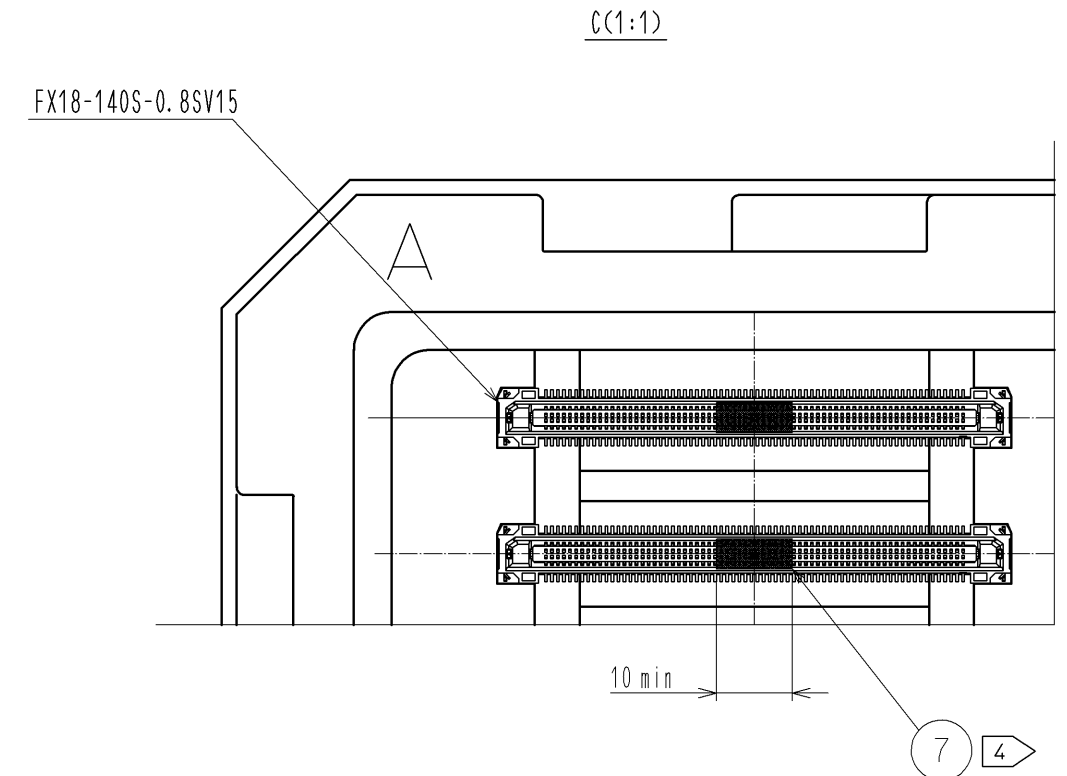
5 DRAWING FOR PACKING(1:2)



8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.  
BE SURE TO CONNECT TO THE SAME CIRCUIT.



HRS

DRAWING NO.	EDC3-343466-00
PART NO.	FX18-140S-0.8SV15
CODE NO.	CL579-0037-0-00
	2/2